

SOT619-8

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 7 x 7 x 0.85 mm

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | Q (quad) |
| Package type descriptive code | HVQFN48 |
| Package type industry code | HVQFN48 |
| Package style descriptive code | HVQFN (thermal enhanced very thin quad flatpack; no leads) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MO-220 |
| Mounting method type | S (surface mount) |
| Issue date | 30-1-2007 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|------|-------|------|
| D | package length | 6.9 | - | 7 | 7.1 | mm |
| E | package width | 6.9 | - | 7 | 7.1 | mm |
| A | seated height | [tbd] | - | 0.85 | 1 | mm |
| A ₂ | package height | [tbd] | - | 0.85 | [tbd] | mm |
| n ₂ | actual quantity of termination | - | - | 48 | - | |

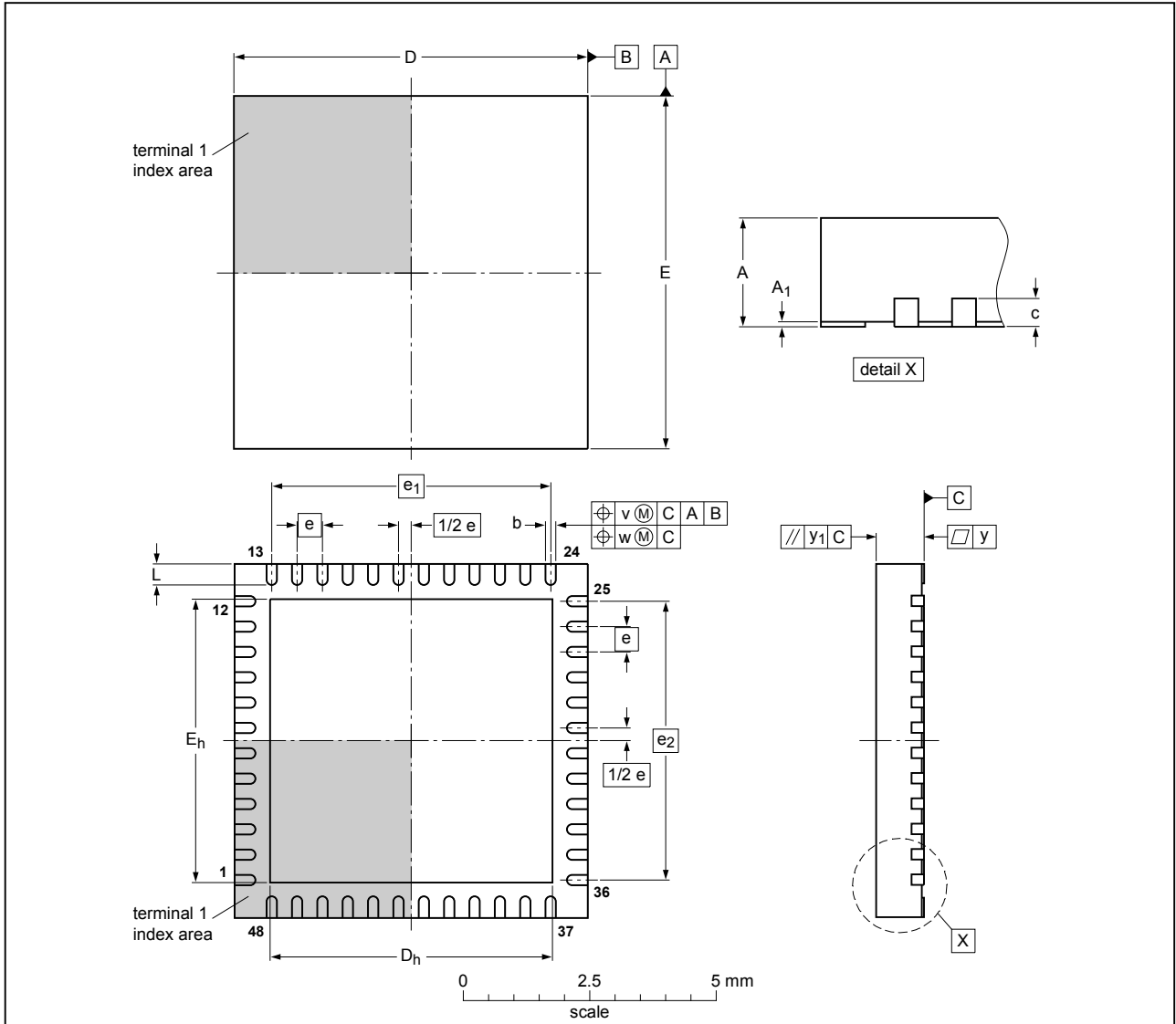


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2. Package outline

HVQFN48: plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 7 x 7 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

| UNIT | A ⁽¹⁾ max | A ₁ | b | c | D ⁽¹⁾ | D _h | E ⁽¹⁾ | E _h | e | e ₁ | e ₂ | L | v | w | y | y ₁ |
|------|-------------------------|----------------|--------------|-----|------------------|----------------|------------------|----------------|-----|----------------|----------------|------------|-----|------|------|----------------|
| mm | 1 | 0.05 0.00 | 0.30 0.18 | 0.2 | 7.1 6.9 | 5.75 5.45 | 7.1 6.9 | 5.75 5.45 | 0.5 | 5.5 | 5.5 | 0.5 0.3 | 0.1 | 0.05 | 0.05 | 0.1 |

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|--------------------|------------|--------|-------|--|------------------------|----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT619-8 | --- | MO-220 | --- | | | 07-01-10 07-01-30 |

Fig. 1. Package outline HVQFN48 (SOT619-8)

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3. Legal information

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